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## COPPER PLATING PROCESSES

<b>KUPFSOL 603</b>	A general purpose cyanide copper plating process for the deposition of semi bright to bright coatings. Suitable as an undercoat prior to bright nickel plating.
<b>KUPFSOL 604</b>	A general purpose Rochelle type cyanide copper plating process for the deposition of semi bright to bright coatings. Suitable as an undercoat prior to bright nickel plating and case hardening of steel.
<b>KUPFSOL 605</b>	A dye based bright acid copper plating process, produces brilliant deposits with good levelling and throwing power. Simple and convenient process control. Ideal for artificial jewellery.
<b>KUPFSOL 606</b>	A dye free bright acid copper plating process, produces brilliant pit free deposits with very good levelling and throwing power. easy to operate. Ideal for plating on plastics.

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